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Notification Number:	20260708002.0	Notification Issued	July 08, 2026
Datasheet for TXE8116			

Change type(s)
Data Sheet/Electrical Specification

Notification Details

Description of Change:		
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.		
 TXE8116 SCPS309B – AUGUST 2025 – REVISED JUNE 2026		
Changes from Revision A (October 2025) to Revision B (June 2026)		Page
• Removed TXE8124 and published in a separate datasheet.....		1
• Updated VQFN package pinout.....		3
• Updated IOL maximum as 10mA in ROC Table.....		4
• Removed redundant Junction Temperature in ROC Table.....		4
• Updated VOH & VOL limits at 1.65V.....		6
• Corrected limits for Bus-hold sustaining current.....		6
• Updated test condition for Bus-hold sustaining current.....		6
• Corrected the description for IBHLO and IBHHO.....		6
• Clarified clearing of INT behavior.....		15
• Added Bus Hold feature description.....		17
• Updated Feature Register Mapping description.....		19
• Added SPI SDO data frame format.....		20
• Added transaction diagrams for single and burst SPI write.....		21
• Added transaction diagram for single and burst SPI read.....		22
• Updated register description for Input_Port_Register.....		26
• Added pseudo-code for SPI write and read.....		52
The datasheet number will be changing.		
Device Family	Change From:	Change To:
TXE8116	SCPS309A	SCPS309B
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/TXE8116		
Reason for Change:	To accurately reflect device characteristics.	
Anticipated impact on Form, Fit, Function, Quality or Reliability:	None	
Changes to product identification resulting from this PCN:	None	

Products Affected:			
TXE8116DGSR	TXE8116RGER		

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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